



1.8 SEC

先進封裝協作型技術團隊

透過高度協作能力，讓不同體系客戶都能成功

C SUN 志聖工業

2026 Q1 Investor's meeting

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward-looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward-looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design in, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations. global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward-looking statements. Except as required by law. C Sun undertakes no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

G2C+ 聯盟：平台化作戰優勢

G2C+ Alliance: The Platform Advantage

Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)

Thermal (熱)
Wet Process (濕製程)
UV/Plasma (光/電漿)

1,800+

聯盟總人數
(Total Alliance Workforce)



AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)



>600

研發人員
(R&D Personnel)

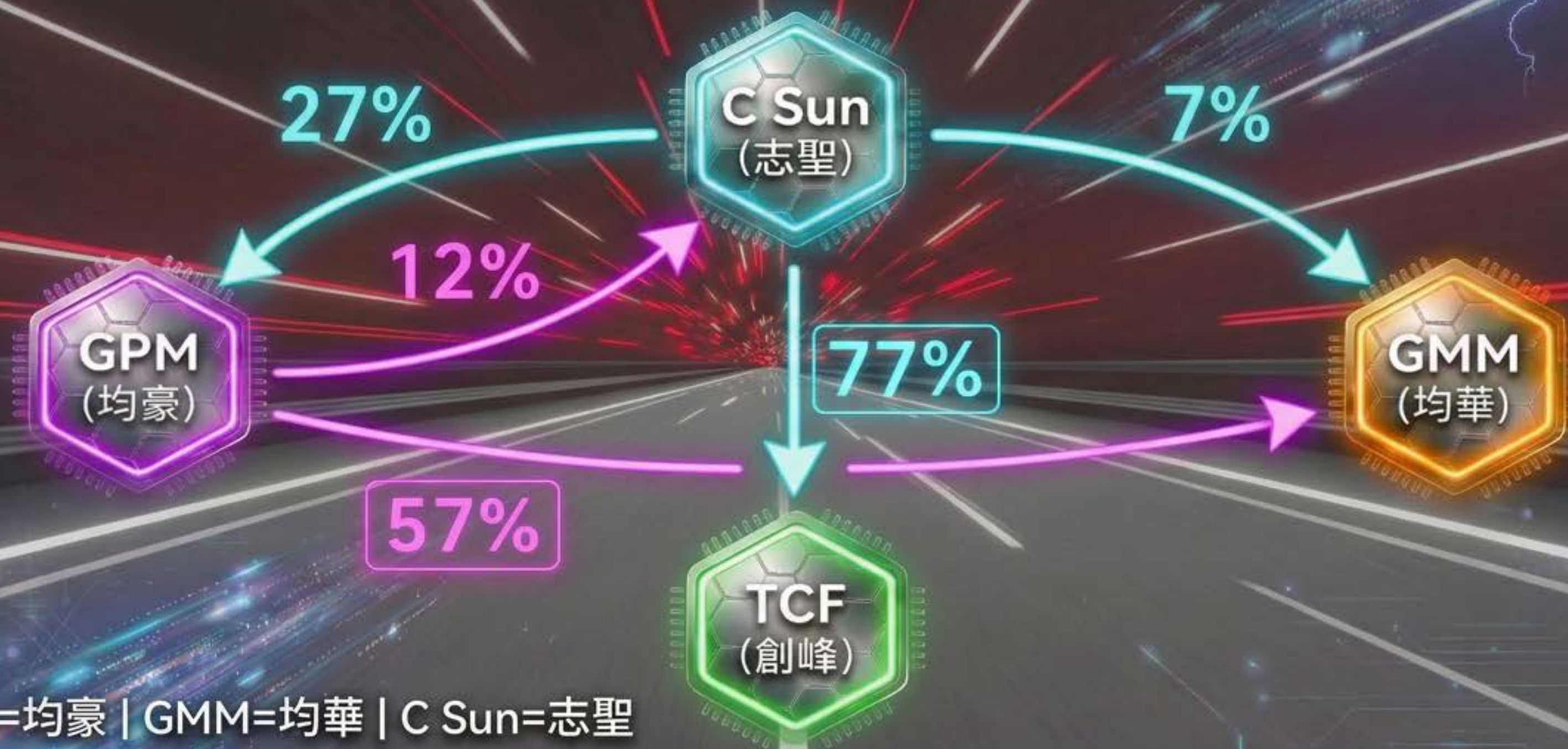


研發團隊規模成長
軟體 + 機構

Die Attach (黏晶)
Chip Sorter (揀晶)

G2C+ ALLIANCE

Cross Holding Structure



AI賽道上的專業協作團隊

連續獲得冠軍車隊肯定



2023:
Excellent Production Support
(卓越量產支援)



2024:
Outstanding Improvement
(傑出持續改善)



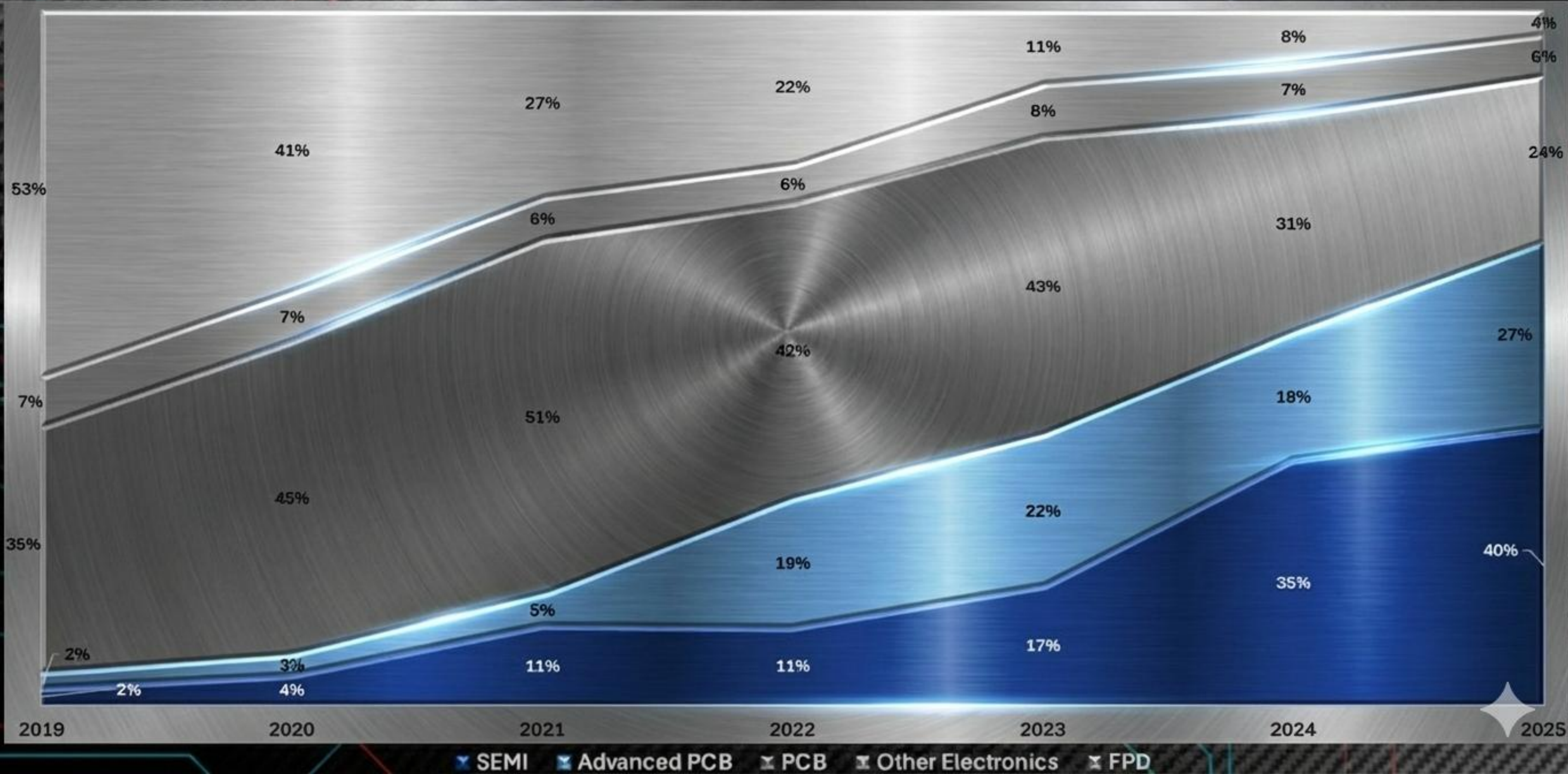
2025:
Excellent Production Support
(卓越量產支援)

財務回顧

(除另予註明者外，金額為新台幣百萬元)

	2026 Jan	2025	4Q25	3Q25	1H25	2024	4Q25 QoQ	2025 YoY
營業收入淨額	994	6,102	1,747	1,536	2,819	4,818	13.7%	26.6%
營業毛利率%		43.3%	44.1%	44.2%	42.3%	41.2%	-0.1ppts	+2.1ppts
營業費用		(1,760)	(493)	(526)	(741)	(1,347)	-6.3%	30.7%
營業費用率%		28.9%	28.2%	34.3%	30.5%	28.0%	-2.3ppts	+0.9ppts
研發費用		(543)	(170)	(164)	(208)	(362)	3.9%	49.8%
研發費用率%		8.9%	9.8%	10.7%	7.4%	7.5%	-0.9ppts	+1.4ppts
營業利益率%		14.5%	15.9%	10.0%	16.1%	13.2%	+5.9ppts	+1.3ppts
營業外收入與支出		243	56	134	54	344	-58.4%	-29.1%
歸屬予母公司業主之本期淨利		830	260	212	358	719	23.1%	15.4%
純益率%		13.6%	14.9%	13.8%	12.7%	14.9%	+1.1ppts	-1.3ppts
每股盈餘(新台幣元)		5.5	1.72	1.4	2.38	4.8	22.9%	14.6%

Revenue Composition



財務亮點：結構性蛻變與獲利創高

Scoreboard

2025 營收 (Revenue)

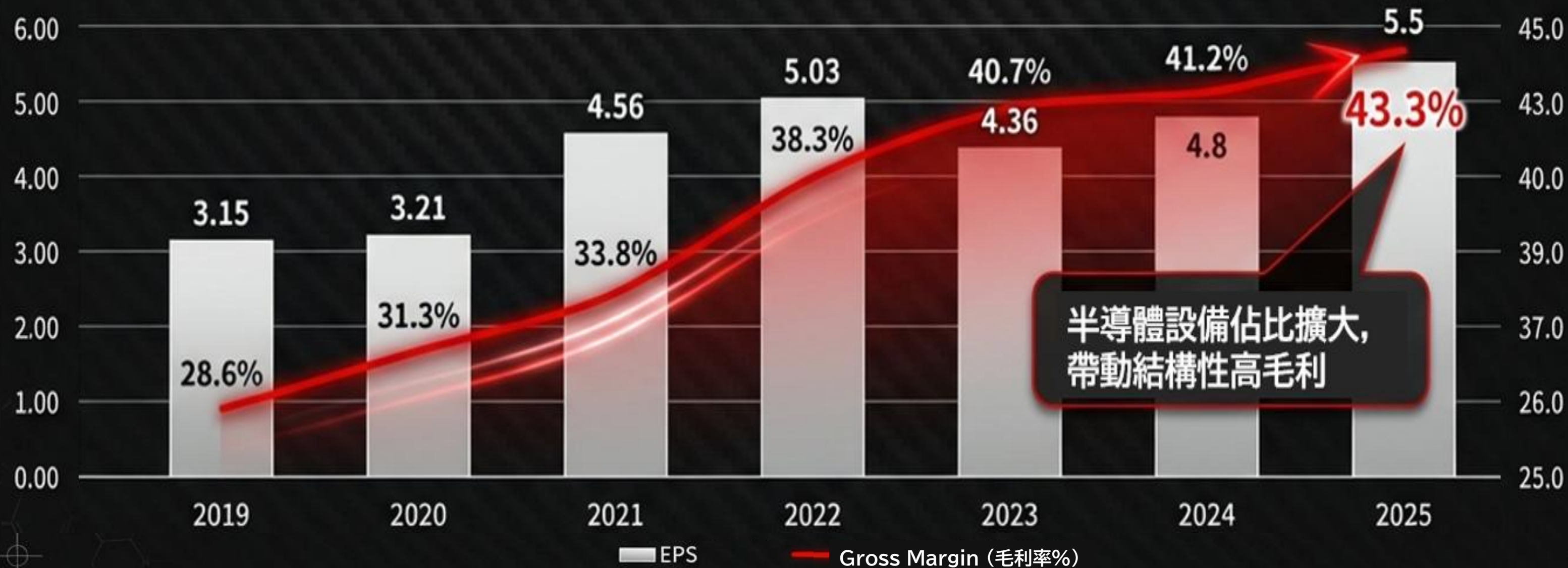
61 億元 Record High
(創歷史新高)

2025 EPS

5.50 元

EPS (NTD\$)

Gross Margin (毛利率%)



2026年開局：單月營收創新高

MoM
+64.60%

↑
MoM

9.94
億元

YoY
+124.10%

↑
YoY

客戶資本支出持續投入，未來成長動
能具延續性。配合客戶交期需求。



TSMC, intel, GF
FOUNDRY ACCESS TRACK

OSAT
ACCESS TRACK

AI SUBSTRATE & HDI
ACCESS TRACK

Advanced Packaging
GRAND CIRCUIT

GRAND CIRCUIT

InFO

SoIC

EMIB

X-CUBE

WMCM

Adv. PLP

SoIC

InFO

FlipChip

FoCoS

FoPLP

CoWoS

CoWoS

CoWoP

CoWoP

CoWoS

ABF

HDI

SAP

mSAP

mSAP

成長引擎I：跟隨領航者 晶圓廠全球在地化

- Foundry 2.0 Glocalization 的大戰略

Foundry's Front End



Advanced Packaging
(Foundry 2.0)

C SUN & G2C+

Germany
(Dresden)

Japan
(Kumamoto)

USA
(Arizona)

Foundry晶圓廠的
資本支出持續上升



成長引擎II: AI晶片多元化帶動製程分流與封裝技術外溢

AI多元化推動
製程分化

OSAT Expansion
(ASE, Amkor, SPIL)

Technology Shift → FOPLP
(Panel Level)

HBM Memory Demand
(Micron, SK Hynix)

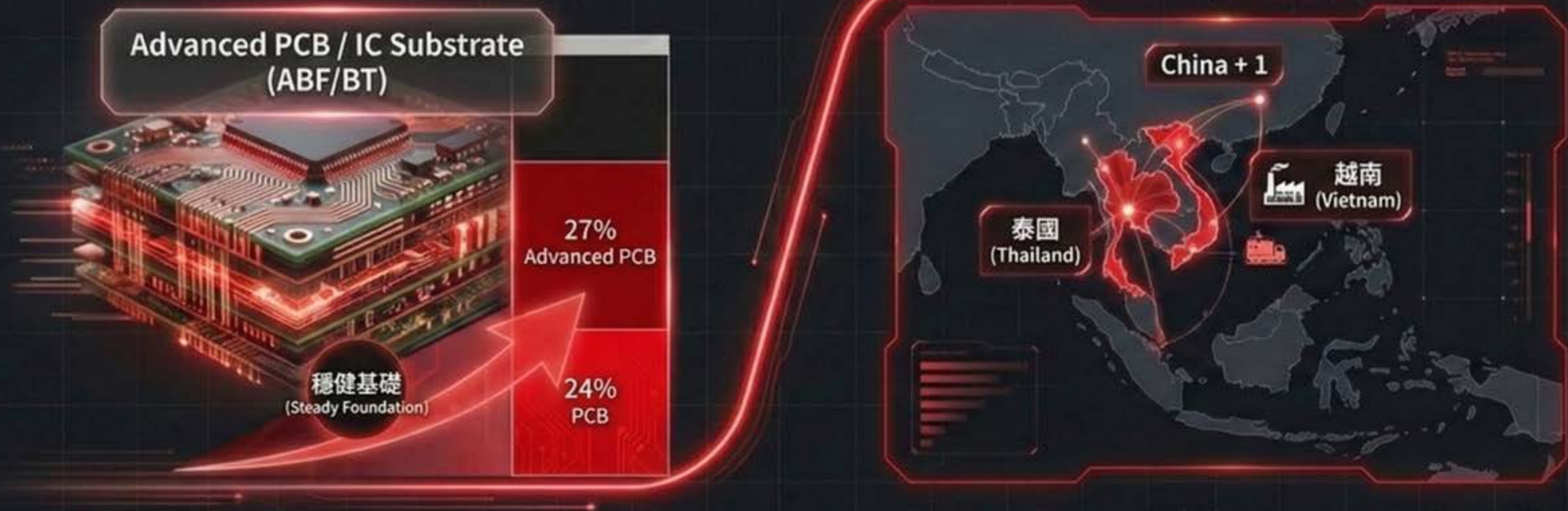
DATA

HBM 擴產帶動熱製程
(Oven) 設備需求提升



成長引擎 III：高階PCB產品占比提升及區域移動

Foundation & Expansion Strategy



產品組合優化帶動**平均售價提升**，獲利結構持續改善。

技術藍圖：全方位製程覆蓋

Technology Roadmap: Full Spectrum Coverage



不僅掌握現有先進製程紅利，更已佈局未來 3 年 新製程需求

研發資源配置與技術升級

R&D Resource Allocation & Tech Upgrade

先進封裝產業鏈新世代製程與設備升級
Next-Gen Processes & Equipment Upgrade for Advanced Packaging Supply Chain

Investment Slope



技術升級期的投入將支持未來3-5年成長動能

築巢引鳳：研發中心與全球擴張

18.2 億 NTD

打造研發中心，為多元
前瞻設備開發奠定基礎。

USA

台中水湳研發中心

(Taichung Shuinan R&D Center)

The Innovation Hub

精科二廠

(Jingke Plant 2)

Capacity Expansion

Japan

14.8 億 NTD

購置廠房與設施，
確保未來產能無虞。

F1 先進封裝大賽

Foundry 主賽道

CoWoS / SoIC / WMCM



OSAT 賽道

PLP / oS / Bumping / CoW / EMIB



AI載板多層板賽道

IC Substrate / HDI

